

## EP 3332 EPOXY ADHESIVE

### ● PRODUCT DESCRIPTION

EP 3332 is a complete product of unfilled 2K-Epoxy adhesive. This product is available in different viscosities. The product can be cured by thermal heat or at room temperature. The mixing ratio is 1:1 by weight. The product is suited for many different applications and has a good temperature resistance. Due to the polarity of the resins it has a good flow characteristic and adhesion to many different substrates, metals and plastics as well. Therefore the product is suited also for potting of pluggers and switches. Special characteristic is the low shrinkage and the excellent resistance against moisture, solvents and acids. Complies with military spec: MIL-A-14042

### ● CURING PROPERTIES

25°C	75°C	100°C	150°C	200°C
16hr.	2hr. 30min.	1 hr. 30min.	20min.	5min.
For maximum chemical and heat resistant properties, 2 hours at 100° C post cure recommended.				

### ● UNCURED PROPERTIES

<b>Color</b>	Beige
<b>Viscosity (mixed)</b>	100.000 mPas
<b>Flash Point (°C)</b>	> 190
<b>Pot Life (@25°C)</b>	4 hours
<b>Density (gr/cm<sup>3</sup>)</b>	Apprx. 1,05
<b>Mix Ratio</b>	1:1



## EP 3330 EPOXY ADHESIVE

### • CURED PROPERTIES

Temperature Resistance (°C)	-65 to 150
Hardness (Shore D)	75 to 85
Volume resistivity (Ohm x cm)	5E+14
Water Absorption (mass-%)	<0.59
Glass Transition Temp.(°C)	+65
CTE (ppm/K)	86
Dielectric Constant (10kHz)	3,4
Dielectric Strength (kV/mm)	440
Lap Shear Strength (Al/Al) (MPa)	15
Lap Shear Strength (Cu/Cu) (MPa)	10
Lap Shear Strength (Steel/Steel) (MPa)	19.3
Elongation at Break (%)	20
Tensile Stress (MPa)	42
E-Modul (MPa)	2000

### • INSTRUCTIONS FOR USE

The surfaces should be free of dust, oil and other dirt in order to obtain an optimal efficient bond.

The components A and B have to be homogenised well, weight out in mixing ration and homogenised with each other for min. 2 minutes.

From now, the pot life time starts and the adhesive has to be applied rapidly. The mixed adhesive should not be applied after the pot life time. It is useful to mix only this quantity of adhesive you can apply during the pot life time.

For curing heat must be applied. In some cases they will cure even at room temperature. But higher temperature will reduce the curing time. For detailed curing information, please look into the technical data sheet.

Shelf life: Store in original, unopened containers for 12 months at room temperature

The resin of part A might cristalize during storage. This process is reversible by heating (1 hour @ 40°C).

